IBGA80 10x10
CASE 503BA
ISSUE A

DATE 05 OCT 2017
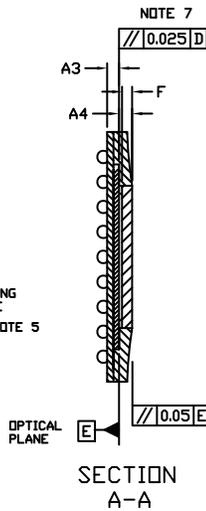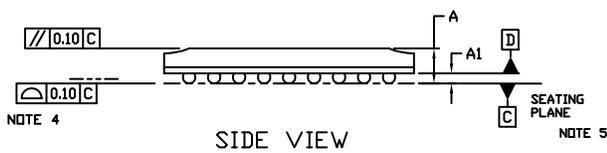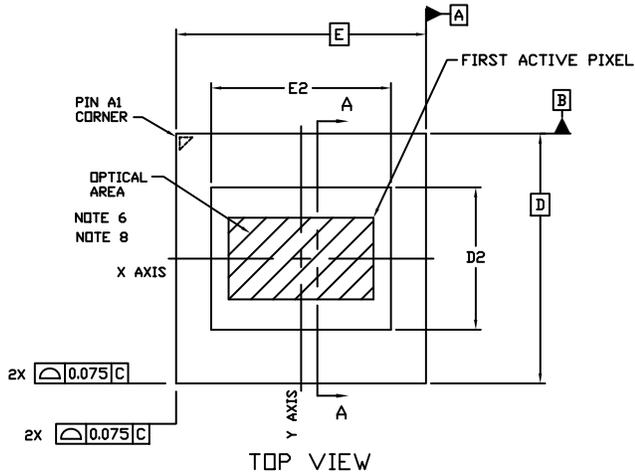
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

2. CONTROLLING DIMENSION: MILLIMETERS

3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
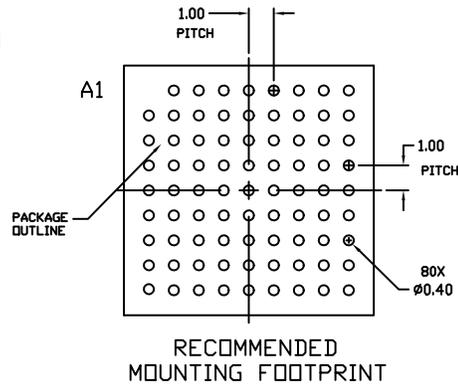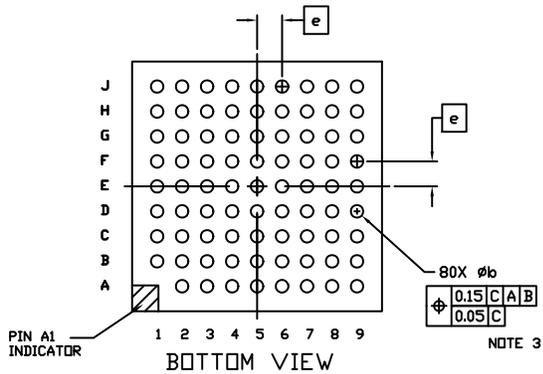
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

6. MAXIMUM ROTATION OF OPTICAL AREA RELATIVE TO D AND E WILL BE 0.5°. OPTICAL AREA IS DEFINED BY THE ACTIVE PIXEL ARRAY. REFER TO THE DEVICE DATASHEET FOR TOTAL ARRAY AND FIRST ACTIVE PIXEL DEFINITIONS.

7. PARALLELISM APPLIES ONLY TO THE OPTICAL AREA.

8. OPTICAL CENTER OFFSET WITH RESPECT TO THE PACKAGE CENTER IS X=0.00 MICRONS, Y=0.00 MICRONS ±75 MICRONS.

DIM	MILLIMETERS	
	MIN.	MAX.
A	---	1.55
A1	0.35	0.45
A3	0.425	0.525
A4	0.475	0.575
b	0.45	0.55
D	10.00 BSC	
D2	5.60	5.80
E	10.00 BSC	
E2	7.10	7.30
e	1.00 BSC	
F	0.36	0.44

TOP VIEW

SIDE VIEW

SECTION A-A

BOTTOM VIEW

RECOMMENDED MOUNTING FOOTPRINT

DOCUMENT NUMBER:	98AON99906F
STATUS:	ON SEMICONDUCTOR STANDARD
REFERENCE:	
DESCRIPTION:	IBGA80 10X10

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ISSUE	REVISION	DATE
O	RELEASED FOR PRODUCTION FROM APTINA POD# AR0237 TO ON SEMICON-DUCTOR. REQ. BY D. TRUHITTE.	07 JUL 2015
A	DRAWING RE–FORMATTED TO ON SEMICONDUCTOR JEDEC STANDARDS. REQ. BY M. FORBIS.	05 OCT 2017